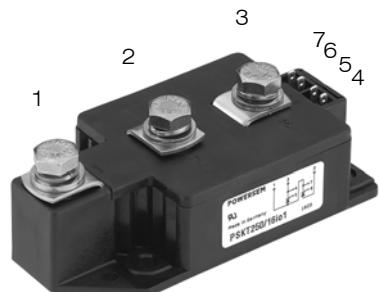


Thyristor Modules Thyristor/Diode Modules

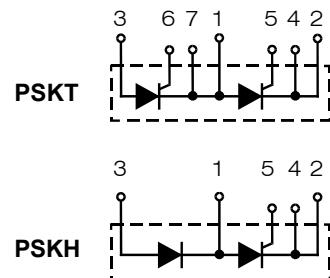
Preliminary Data Sheet

PSKT 250 $I_{TRMS} = 2 \times 450 \text{ A}$
PSKH 250 $I_{TAVM} = 2 \times 287 \text{ A}$
 $V_{RRM} = 800-1800 \text{ V}$

V_{RSM}	V_{RRM}	Type	
V_{DSM}	V_{DRM}		
V	V	Version 1	Version 1
900	800	PSKT 250/08io1	PSKH 250/08io1
1300	1200	PSKT 250/12io1	PSKH 250/12io1
1500	1400	PSKT 250/14io1	PSKH 250/14io1
1700	1600	PSKT 250/16io1	PSKH 250/16io1
1900	1800	PSKT 250/18io1	PSKH 250/18io1



Symbol	Test Conditions		Maximum Ratings	
I_{TRMS}, I_{FRMS}	$T_{VJ} = T_{VJM}$		450	A
I_{TAVM}, I_{FAVM}	$T_c = 85^\circ\text{C}$; 180° sine		287	A
I_{TSM}, I_{FSM}	$T_{VJ} = 45^\circ\text{C}$; $V_R = 0$	t = 10 ms (50 Hz), sine t = 8.3 ms (60 Hz), sine	9000	A
	$T_{VJ} = T_{VJM}$ $V_R = 0$	t = 10 ms (50 Hz), sine t = 8.3 ms (60 Hz), sine	9600	A
$\int i^2 dt$	$T_{VJ} = 45^\circ\text{C}$ $V_R = 0$	t = 10 ms (50 Hz), sine t = 8.3 ms (60 Hz), sine	7800	A
	$T_{VJ} = T_{VJM}$ $V_R = 0$	t = 10 ms (50 Hz), sine t = 8.3 ms (60 Hz), sine	8500	A
$(di/dt)_{cr}$	$T_{VJ} = T_{VJM}$ $f = 50 \text{ Hz}$, $t_p = 200 \mu\text{s}$ $V_D = 2/3 V_{DRM}$ $I_G = 1 \text{ A}$ $di_G/dt = 1 \text{ A}/\mu\text{s}$	repetitive, $I_T = 860 \text{ A}$ non repetitive, $I_T = 290 \text{ A}$	100	$\text{A}/\mu\text{s}$
$(dv/dt)_{cr}$	$T_{VJ} = T_{VJM}$; $R_{GK} = \infty$; method 1 (linear voltage rise)	$V_{DR} = 2/3 V_{DRM}$	1000	$\text{V}/\mu\text{s}$
P_{GM}	$T_{VJ} = T_{VJM}$ $I_T = I_{TAVM}$	$t_p = 30 \mu\text{s}$ $t_p = 500 \mu\text{s}$	120	W
P_{GAV}			60	W
V_{RGM}			20	W
T_{VJ}			-40...+140	$^\circ\text{C}$
T_{VJM}			140	$^\circ\text{C}$
T_{stg}			-40...+125	$^\circ\text{C}$
V_{ISOL}	50/60 Hz, RMS $I_{ISOL} \leq 1 \text{ mA}$	t = 1 min t = 1 s	3000 3600	$\text{V}-$
M_d	Mounting torque (M5) Terminal connection torque (M8)		2.5-5/22-44 Nm/lb.in 12-15/106-132 Nm/lb.in	
Weight	Typical including screws		320	g



Features

- International standard package
- Direct copper bonded Al_2O_3 -ceramic base plate
- Planar passivated chips
- Isolation voltage 3600 V_{AC}
- UL registered, E 148688
- Keyed gate/cathode twin pins

Applications

- Motor control
- Power converter
- Heat and temperature control for industrial furnaces and chemical processes
- Lighting control
- Contactless switches

Advantages

- Space and weight savings
- Simple mounting with two screws
- Improved temperature and power cycling capability
- Reduced protection circuits

Data according to IEC 60747 and refer to a single thyristor/diode unless otherwise stated.

POWERSEM

Symbol	Test Conditions	Characteristic Values	
I_{RRM}	$T_{VJ} = T_{VJM}$; $V_R = V_{RRM}$; $V_D = V_{DRM}$	70	mA
I_{DRM}		40	mA
V_T, V_F	$I_T, I_F = 600 \text{ A}$; $T_{VJ} = 25^\circ\text{C}$	1.36	V
V_{TO}	For power-loss calculations only ($T_{VJ} = 140^\circ\text{C}$)	0.85	V
r_T		0.82	$\text{m}\Omega$
V_{GT}	$V_D = 6 \text{ V}$; $T_{VJ} = 25^\circ\text{C}$	2	V
	$T_{VJ} = -40^\circ\text{C}$	3	V
I_{GT}	$V_D = 6 \text{ V}$; $T_{VJ} = 25^\circ\text{C}$	150	mA
	$T_{VJ} = -40^\circ\text{C}$	200	mA
V_{GD}	$T_{VJ} = T_{VJM}$; $V_D = 2/3 V_{DRM}$	0.25	V
I_{GD}		10	mA
I_L	$T_{VJ} = 25^\circ\text{C}$; $t_p = 30 \mu\text{s}$; $V_D = 6 \text{ V}$ $I_G = 0.45 \text{ A}$; $di_G/dt = 0.45 \text{ A}/\mu\text{s}$	200	mA
I_H	$T_{VJ} = 25^\circ\text{C}$; $V_D = 6 \text{ V}$; $R_{GK} = \infty$	150	mA
t_{gd}	$T_{VJ} = 25^\circ\text{C}$; $V_D = 1/2 V_{DRM}$ $I_G = 1 \text{ A}$; $di_G/dt = 1 \text{ A}/\mu\text{s}$	2	μs
t_q	$T_{VJ} = T_{VJM}$; $I_T = 300 \text{ A}$, $t_p = 200 \mu\text{s}$; $-di/dt = 10 \text{ A}/\mu\text{s}$ typ. $V_R = 100 \text{ V}$; $dv/dt = 50 \text{ V}/\mu\text{s}$; $V_D = 2/3 V_{DRM}$	200	μs
Q_s	$T_{VJ} = 125^\circ\text{C}$; $I_T, I_F = 400 \text{ A}$, $-di/dt = 50 \text{ A}/\mu\text{s}$	760	μC
I_{RM}		275	A
R_{thJC}	per thyristor/diode; DC current	0.129	K/W
	per module	0.0645	K/W
R_{thJK}	per thyristor/diode; DC current	0.169	K/W
	per module	0.0845	K/W
d_s	Creepage distance on surface	12.7	mm
d_A	Strike distance through air	9.6	mm
a	Maximum allowable acceleration	50	m/s^2

Optional accessories for modules

Keyed gate/cathode twin plugs with wire length = 350 mm, gate = yellow, cathode = red

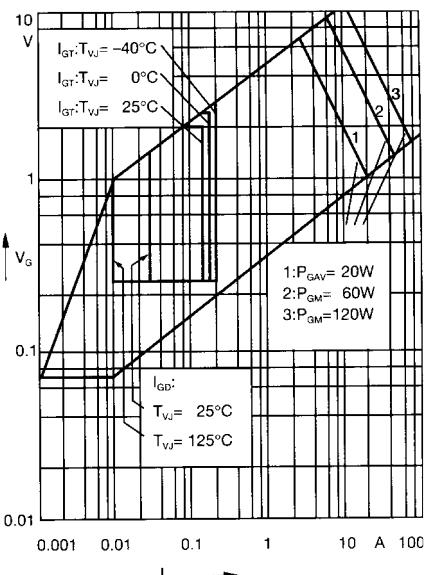


Fig. 1 Gate trigger characteristics

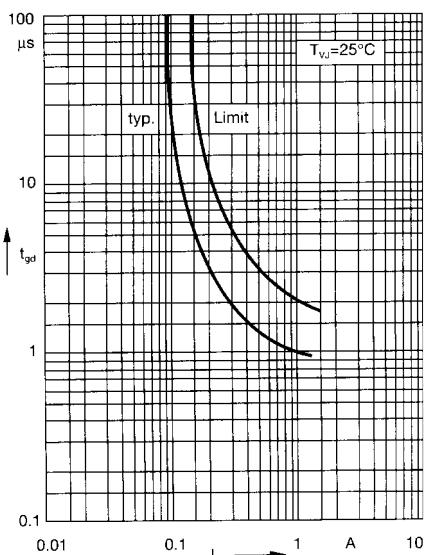
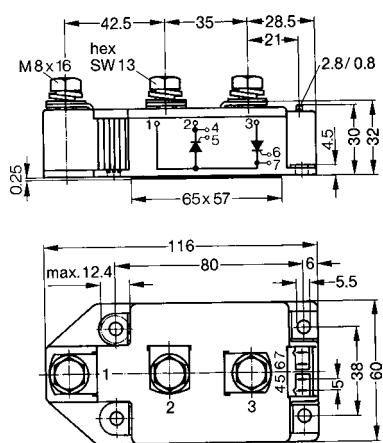


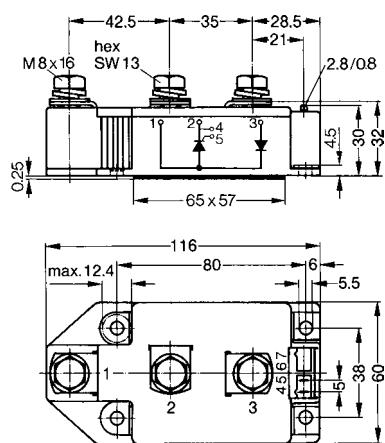
Fig. 2 Gate trigger delay time

Dimensions in mm (1 mm = 0.0394")

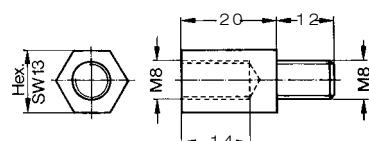
PSKT



PSKH



Threaded spacer for higher Anode/Cathode construction:
Type **ZY 250**, material brass



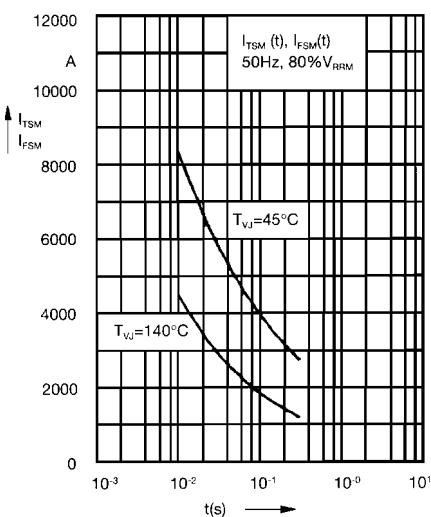


Fig. 3 Surge overload current
 I_{TSM}, I_{FSM} : Crest value, t: duration

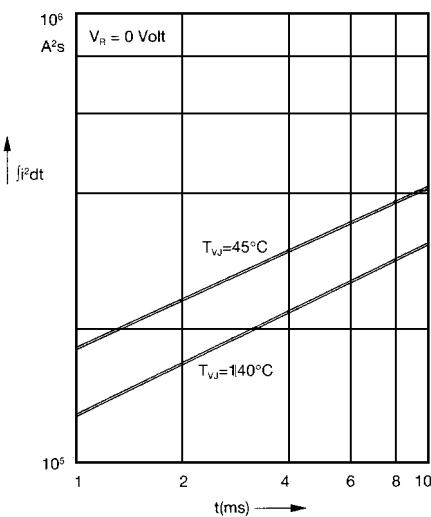


Fig. 4 $\int I^2 dt$ versus time (1-10 ms)

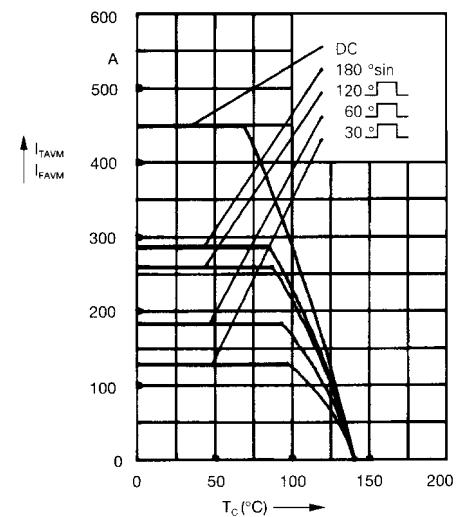


Fig. 4a Maximum forward current at case temperature

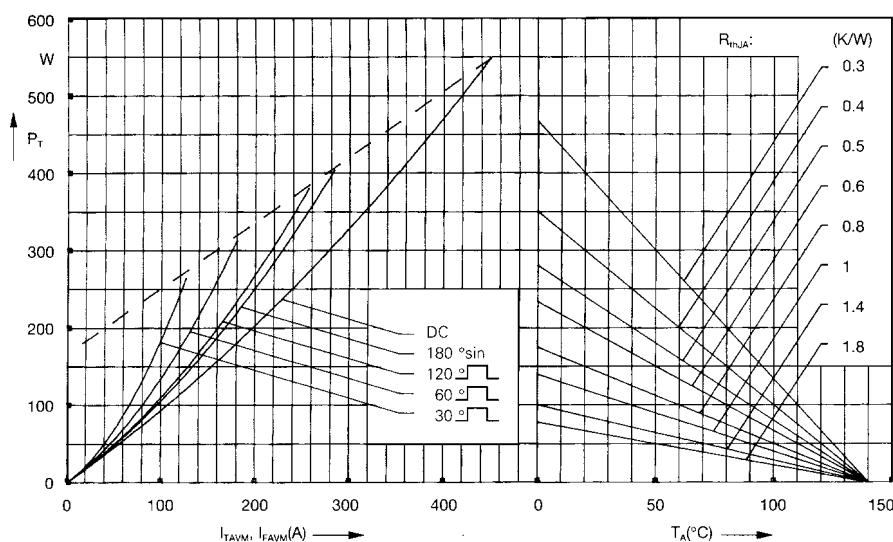


Fig. 5 Power dissipation versus on-state current and ambient temperature (per thyristor or diode)

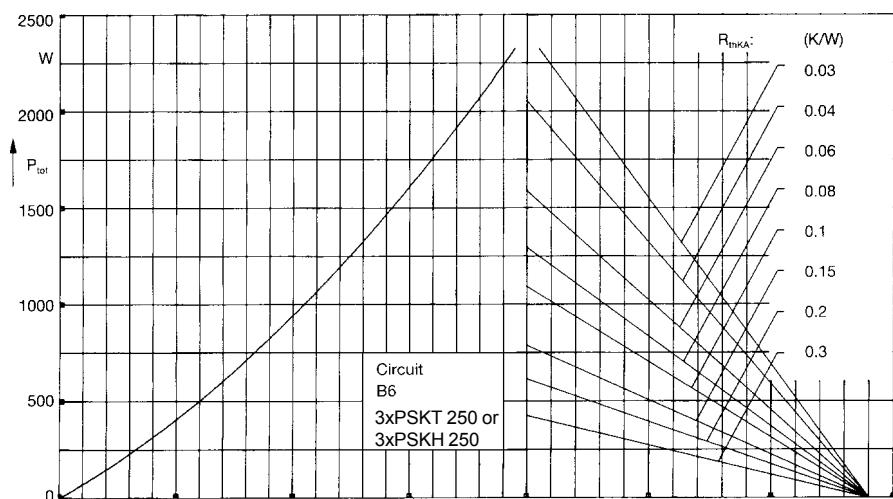


Fig. 6 Three phase rectifier bridge:
Power dissipation versus direct output current and ambient temperature

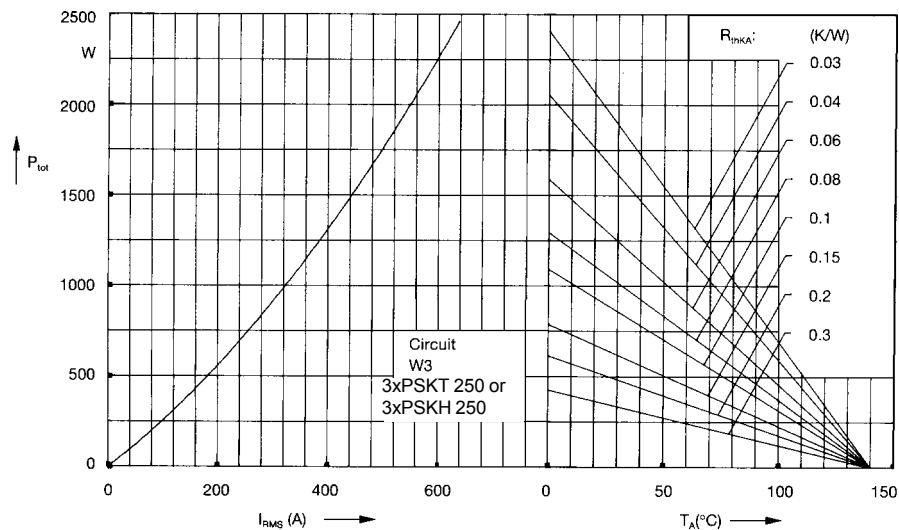


Fig. 7 Three phase AC-controller:
Power dissipation versus RMS
output current and ambient
temperature

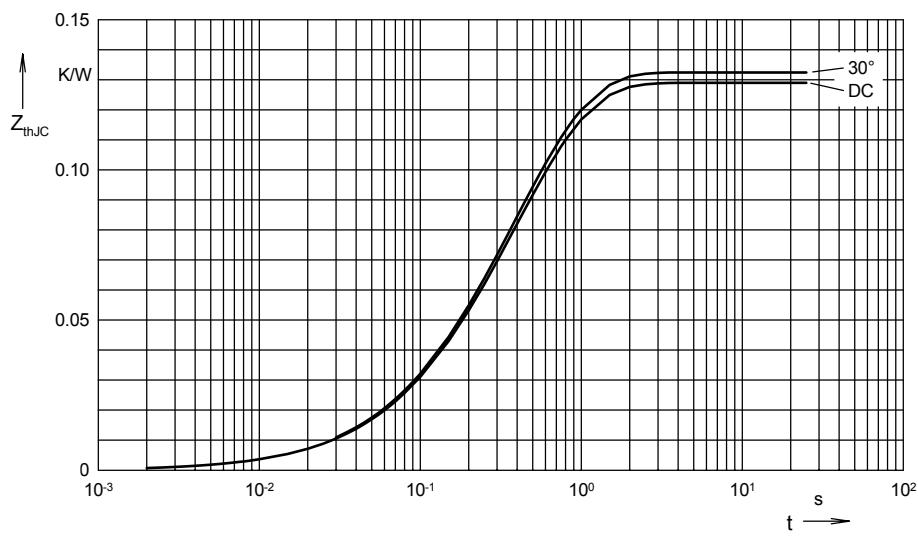


Fig. 8 Transient thermal impedance
junction to case (per thyristor or
diode)

R_{thJC} for various conduction angles d:

d	R_{thJC} (K/W)
DC	0.129
180°C	0.131
120°C	0.131
60°C	0.132
30°C	0.132

Constants for Z_{thJC} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.0035	0.099
2	0.0165	0.168
3	0.1091	0.456

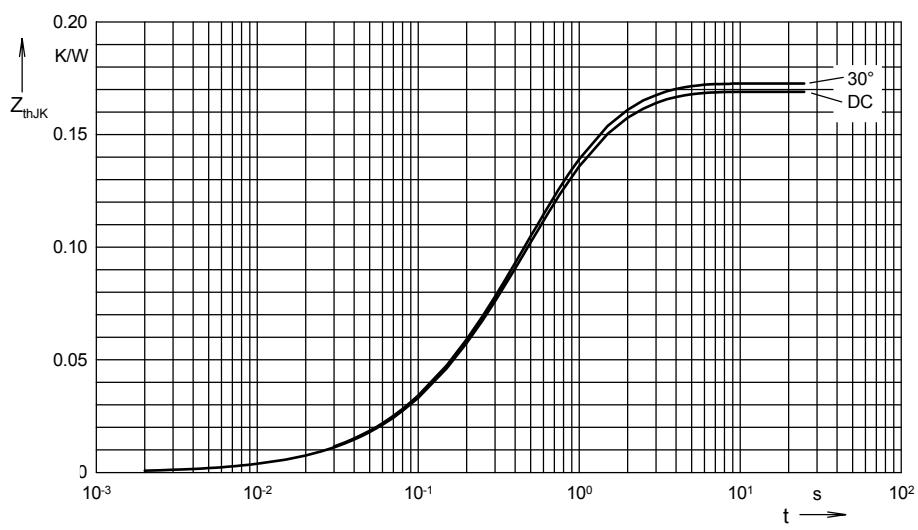


Fig. 9 Transient thermal impedance
junction to heatsink (per thyristor or
diode)

R_{thJK} for various conduction angles d:

d	R_{thJK} (K/W)
DC	0.169
180°C	0.171
120°C	0.172
60°C	0.172
30°C	0.173

Constants for Z_{thJK} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.0033	0.099
2	0.0159	0.168
3	0.1053	0.456
4	0.04	1.36